502641322 01/17/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2687930

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAE YONG LEE	01/16/2014

RECEIVING PARTY DATA

Name:	SK HYNIX INC.	
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB	
City:	ICHEON-SI GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14158117

CORRESPONDENCE DATA

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Correspondent Name: WILLIAM PARK & ASSOCIATES PATENT LTD.

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ATTORNEY DOCKET NUMBER:	PA1535-0	
NAME OF SUBMITTER:	WOOCHOON W. PARK	
Signature:	/Woochoon W. Park/	
Date:	01/17/2014	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 1

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PATENT REEL: 031996 FRAME: 0623

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention	SEMICONDUCTOR CHIP, STACK CHIP INCLUDING THE SAME, AND TESTING METHOD THEREOF		
Declaration	As the below named inventor(s), I hereby declare that: The declaration is directed to: \[\text{\text{\text{The attached application, or}}}\] United States application or PCT international application number \(\text{\t		
	NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledge, and other good and valuable consideration, I, by these presents do sell, assign and transfer unto said assignee(s) SK Hynix Inc.		
	ıl-eub, Icheon-si, Gyeonggi-do 467-734, Korea,		
Assignment	and the heirs, successors, assigns and legal representatives of the assignee (s and exclusive right to the said invention in the United States and in its possessions and in any and all foreign countries any and all improvements the entire rights, title and interest in and to any and all Patents which may be therefore in the United States. I hereby authorize and request the Director of Patent and Trademark Office to issue said United States Patent to said assignee (entire right, title, and interest in and to the same, for his sole use and for the united legal representatives, to the full end of the term for which said Patent may be grafully and entirely as the same would have been held by me had this assignment not been made. I agree promptly upon request of the assignee(s), its heirs, successors, assignment and the invention set forth therein, and to execute and deliver withor compensation any power of attorney, Assignment, application, whether		
Parket and the second s	continuation, divisional or reissue, or other papers that may be necessary. I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
	I further covenant that assignee(s) will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to me and will testify as to the same in any litigation related thereto and will promptly execute and deliver to assignee(s) or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.		
	Inventor Name (First Middle LAST):	Tae Yong LEE	
Legal Name Of Inventor	Inventor Signature:	Tae ymg Lee	
	Date:	JANUARY 16, 2014	

PATENT REEL: 031996 FRAME: 0624

RECORDED: 01/17/2014